

C3M0021120J2

Silicon Carbide Power MOSFET
N-Channel Enhancement Mode

Features

- 3rd generation SiC MOSFET technology
- Optimized package with separate driver source pin
- Larger drain tab for better thermal performance
- High blocking voltage with low on-resistance
- High-speed switching with low capacitances
- Fast intrinsic diode with low reverse recovery (Q_{rr})
- Halogen free, RoHS compliant

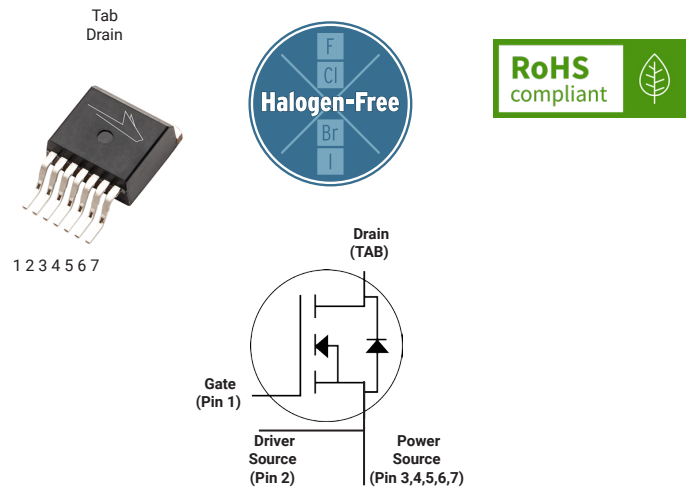
Benefits

- Reduce switching losses and minimize gate ringing
- Higher system efficiency
- Reduce cooling requirements
- Increase power density
- Increase system switching frequency

Applications

- Motor Control
- EV Battery Chargers
- High Voltage DC/DC Converters

Package



Part Number	Package	Marking
C3M0021120J2	TO-263-7XL	C3M0021120J2

Key Parameters

Parameter	Symbol	Min.	Typ.	Max	Unit	Conditions	Note
Drain - Source Voltage	V_{DS}			1200	v	$T_c = 25^\circ\text{C}$	
Maximum Gate - Source Voltage	$V_{GS(max)}$	-8		+19		Transient	
Operational Gate-Source Voltage	$V_{GS op}$		-4/15			Static	Note 1
DC Continuous Drain Current	I_D			114	A	$V_{GS} = 15\text{ V}, T_c = 25^\circ\text{C}, T_J \leq 175^\circ\text{C}$	Fig. 19
				83		$V_{GS} = 15\text{ V}, T_c = 100^\circ\text{C}, T_J \leq 175^\circ\text{C}$	Note 2
Pulsed Drain Current	I_{DM}			248		t_{Pmax} limited by T_{Jmax} $V_{GS} = 15\text{ V}, T_c = 25^\circ\text{C}$	Fig. 22
Power Dissipation	P_D			500	W	$T_c = 25^\circ\text{C}, T_J = 175^\circ\text{C}$	Fig. 20
Operating Junction and Storage Temperature	T_J, T_{stg}			-40 to +175	°C		
Solder Temperature	T_L			260		According to JEDEC J-STD-020	

Note (1): Recommended turn-on gate voltage is 15V with $\pm 5\%$ regulation tolerance, see Application Note PRD-04814 for additional details

Note (2): Verified by design


Electrical Characteristics ($T_c = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Min.	Typ.	Max.	Unit	Test Conditions	Note
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	1200			V	$V_{GS} = 0\text{ V}, I_D = 100\ \mu\text{A}$	
$V_{GS(th)}$	Gate Threshold Voltage	1.8	2.9	3.8	V	$V_{DS} = V_{GS}, I_D = 17.10\ \text{mA}$	Fig. 11
			2.3		V	$V_{DS} = V_{GS}, I_D = 17.10\ \text{mA}, T_J = 175^\circ\text{C}$	
I_{DSS}	Zero Gate Voltage Drain Current		1	50	μA	$V_{DS} = 1200\ \text{V}, V_{GS} = 0\ \text{V}$	
I_{GSS}	Gate-Source Leakage Current		10	250	nA	$V_{GS} = 15\ \text{V}, V_{DS} = 0\ \text{V}$	
$R_{DS(on)}$	Drain-Source On-State Resistance		21	29	m Ω	$V_{GS} = 15\ \text{V}, I_D = 62.12\ \text{A}$	Fig. 4, 5, 6
			35			$V_{GS} = 15\ \text{V}, I_D = 62.12\ \text{A}, T_J = 175^\circ\text{C}$	
g_{fs}	Transconductance		38		S	$V_{DS} = 20\ \text{V}, I_{DS} = 62.12\ \text{A}$	Fig. 7
			35			$V_{DS} = 20\ \text{V}, I_{DS} = 62.12\ \text{A}, T_J = 175^\circ\text{C}$	
C_{iss}	Input Capacitance		5100		pF	$V_{GS} = 0\ \text{V}, V_{DS} = 0\ \text{V to } 1000\ \text{V}$	Fig. 17, 18
C_{oss}	Output Capacitance		174			$f = 100\ \text{kHz}$	
C_{rss}	Reverse Transfer Capacitance		11			$V_{AC} = 25\ \text{mV}$	
E_{oss}	C_{oss} Stored Energy		98		μJ	$V_{DS} = 1000\ \text{V}, f = 100\ \text{kHz}$	Fig. 16
$C_{o(er)}$	Effective Output Capacitance (Energy Related)		210		pF	$V_{GS} = 0\ \text{V}, V_{DS} = 0\ \text{to } 800\ \text{V}$	Note: 3
$C_{o(tr)}$	Effective Output Capacitance (Time Related)		323				
E_{ON}	Turn-On Switching Energy (Body Diode FWD)		1.7		mJ	$V_{DS} = 800\ \text{V}, V_{GS} = -4\ \text{V}/15\ \text{V}, I_D = 62.12\ \text{A}, R_{G(ext)} = 2.5\ \Omega, L = 59\ \mu\text{H}, T_J = 175^\circ\text{C}$ FWD = Internal Body Diode	Fig. 26, 28
E_{OFF}	Turn-Off Switching Energy (Body Diode FWD)		0.3				
$t_{d(on)}$	Turn-On Delay Time		15		ns	$V_{DD} = 800\ \text{V}, V_{GS} = -4\ \text{V}/15\ \text{V}, I_D = 62.12\ \text{A}, R_{G(ext)} = 2.5\ \Omega, L = 59\ \mu\text{H}, T_J = 25^\circ\text{C}$ Timing relative to V_{DS} Inductive load	Fig. 27, 28
t_r	Rise Time		34				
$t_{d(off)}$	Turn-Off Delay Time		54				
t_f	Fall Time		13				
$R_{G(int)}$	Internal Gate Resistance		2.9		Ω	$f = 1\ \text{MHz}, V_{AC} = 25\ \text{mV}$	
Q_{gs}	Gate to Source Charge		60		nC	$V_{DS} = 800\ \text{V}, V_{GS} = -4\ \text{V}/15\ \text{V}$ $I_D = 62.12\ \text{A}$ Per IEC60747-8-4 pg 21	Fig. 12
Q_{gd}	Gate to Drain Charge		45				
Q_g	Total Gate Charge		169				

Note (3): $C_{o(er)}$, a lumped capacitance that gives same stored energy as C_{oss} while V_{ds} is rising from 0 to 800V
 $C_{o(tr)}$, a lumped capacitance that gives same charging time as C_{oss} while V_{ds} is rising from 0 to 800V


Reverse Diode Characteristics ($T_c = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Typ.	Max.	Unit	Test Conditions	Note
V_{SD}	Diode Forward Voltage	4.9		V	$V_{GS} = -4\text{ V}, I_{SD} = 31.1\text{ A}, T_J = 25^\circ\text{C}$	Fig. 8, 9, 10
		4.4		V	$V_{GS} = -4\text{ V}, I_{SD} = 31.1\text{ A}, T_J = 175^\circ\text{C}$	
I_S	Continuous Diode Forward Current		85	A	$V_{GS} = -4\text{ V}, T_c = 25^\circ\text{C}$	
I_{SM}	Diode pulse Current		248	A	$V_{GS} = -4\text{ V}$, pulse width t_p limited by T_{Jmax}	
t_{rr}	Reverse Recover time	16		ns	$V_{GS} = -4\text{ V}, I_{SD} = 62.12\text{ A}, V_R = 800\text{ V}$ $di_F/dt = 5300\text{ A}/\mu\text{s}, T_J = 25^\circ\text{C}$	
Q_{rr}	Reverse Recovery Charge	416		nC		
I_{rrm}	Peak Reverse Recovery Current	44		A		
t_{rr}	Reverse Recover time	22		ns	$V_{GS} = -4\text{ V}, I_{SD} = 62.12\text{ A}, V_R = 800\text{ V}$ $di_F/dt = 2240\text{ A}/\mu\text{s}, T_J = 25^\circ\text{C}$	
Q_{rr}	Reverse Recovery Charge	268		nC		
I_{rrm}	Peak Reverse Recovery Current	21		A		

Thermal Characteristics

Symbol	Parameter	Typ.	Unit	Test Conditions	Note
$R_{\theta JC}$	Thermal Resistance from Junction to Case	0.23	$^\circ\text{C}/\text{W}$		Fig. 21



Typical Performance

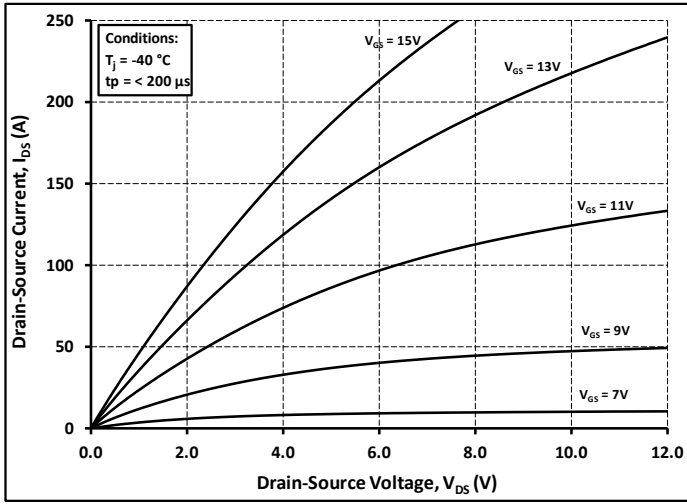


Figure 1. Output Characteristics $T_J = -40\text{ }^\circ\text{C}$

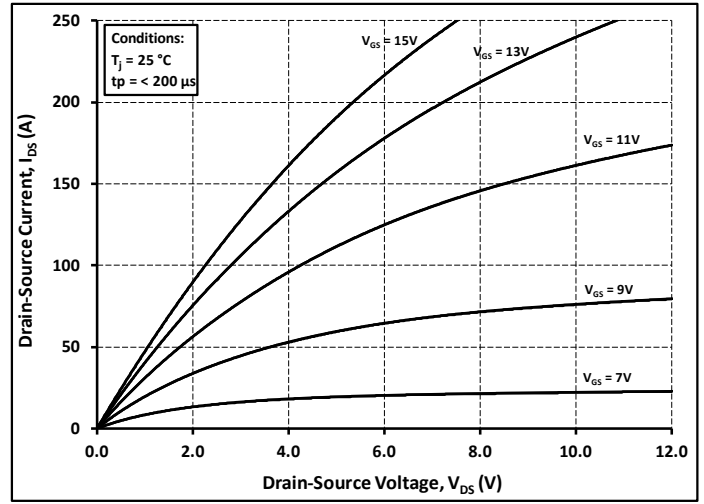


Figure 2. Output Characteristics $T_J = 25\text{ }^\circ\text{C}$

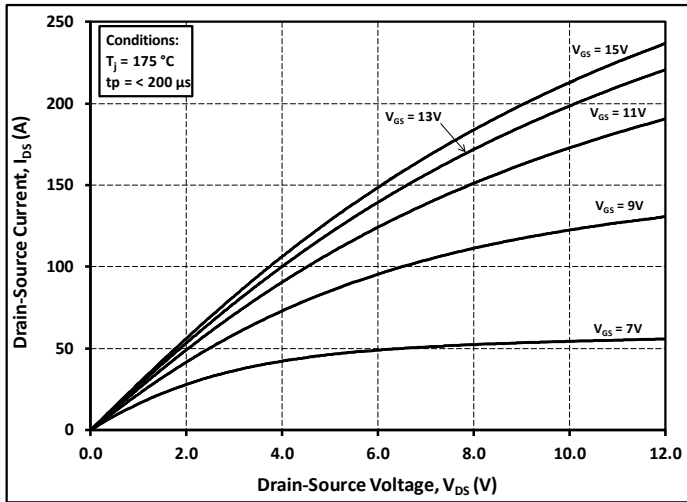


Figure 3. Output Characteristics $T_J = 175\text{ }^\circ\text{C}$

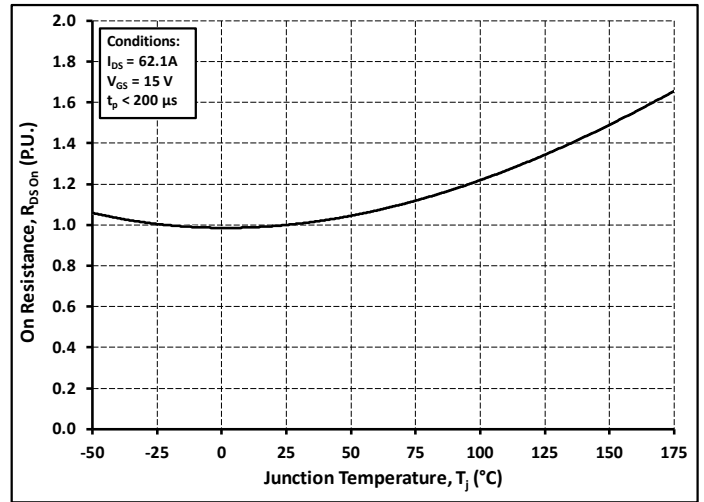


Figure 4. Normalized On-Resistance vs. Temperature

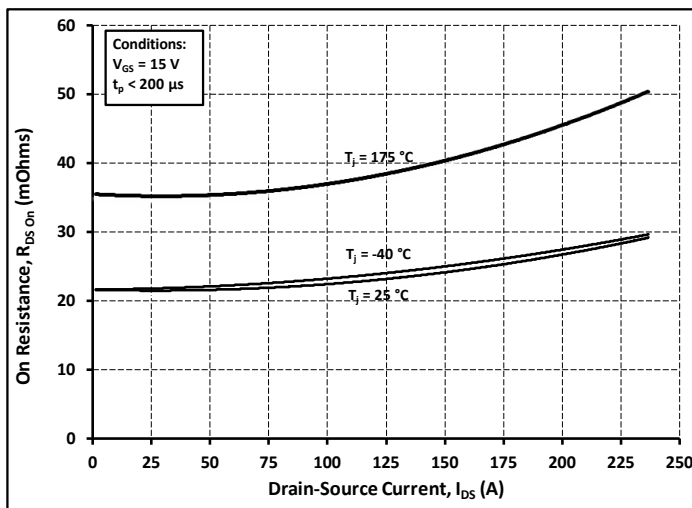


Figure 5. On-Resistance vs. Drain Current For Various Temperatures

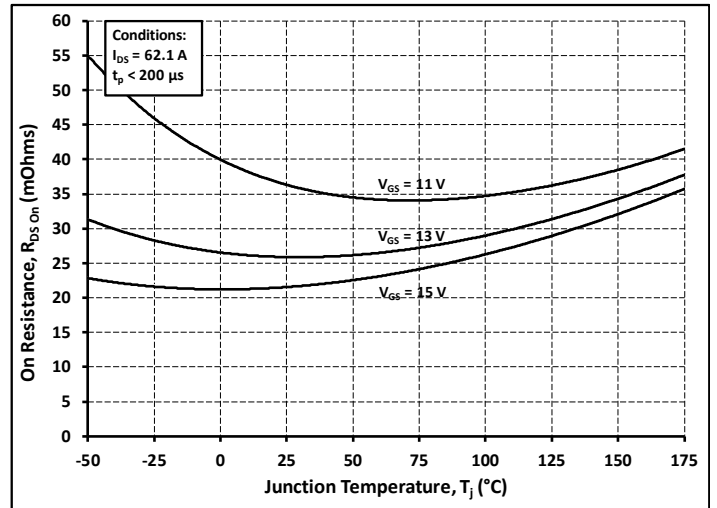


Figure 6. On-Resistance vs. Temperature For Various Gate Voltage



Typical Performance

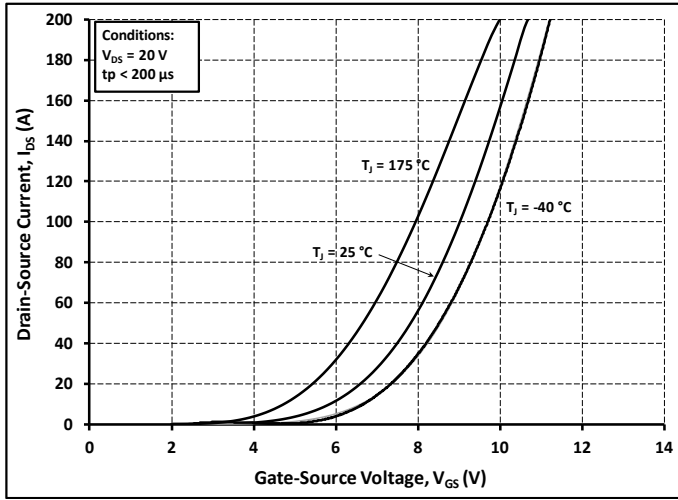


Figure 7. Transfer Characteristic for Various Junction Temperatures

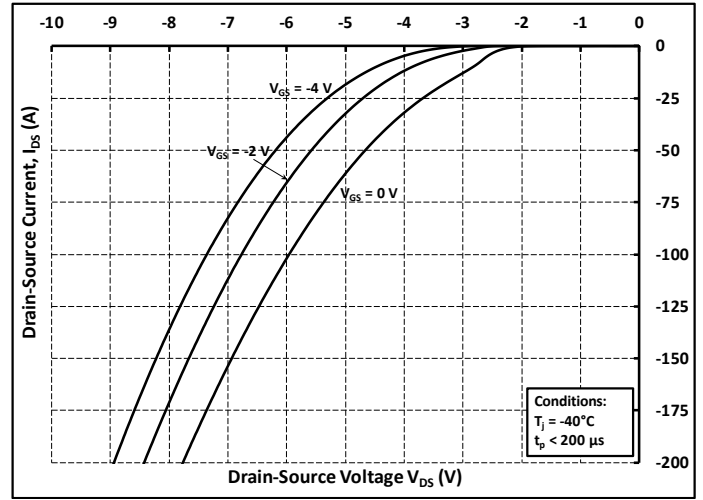


Figure 8. Body Diode Characteristic at -40 °C

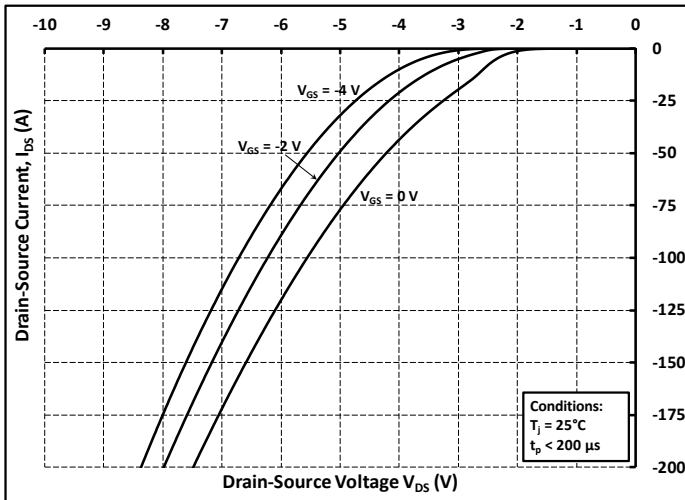


Figure 9. Body Diode Characteristic at 25 °C

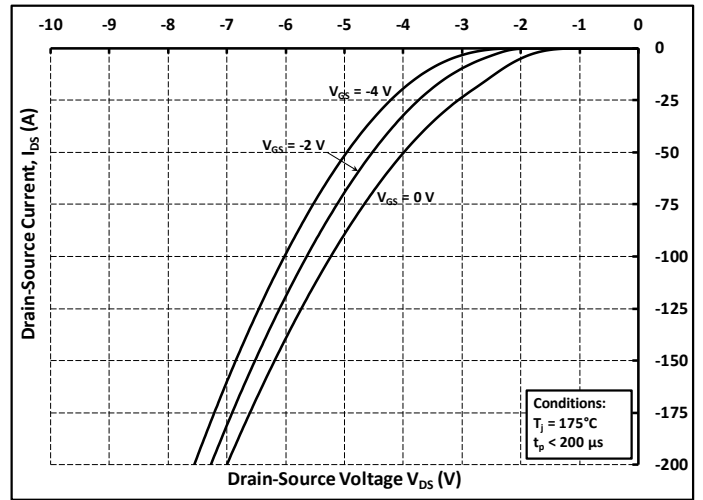


Figure 10. Body Diode Characteristic at 175 °C

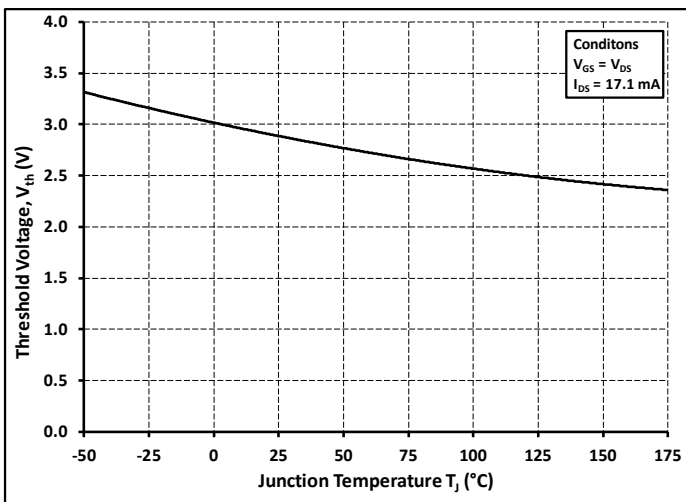


Figure 11. Threshold Voltage vs. Temperature

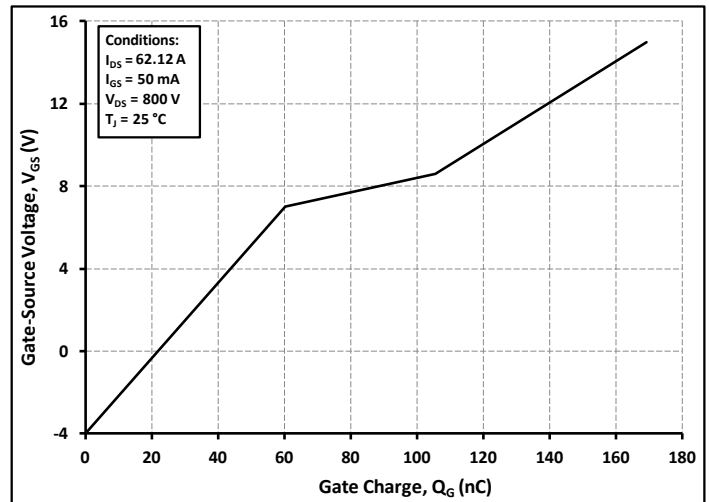


Figure 12. Gate Charge Characteristics



Typical Performance

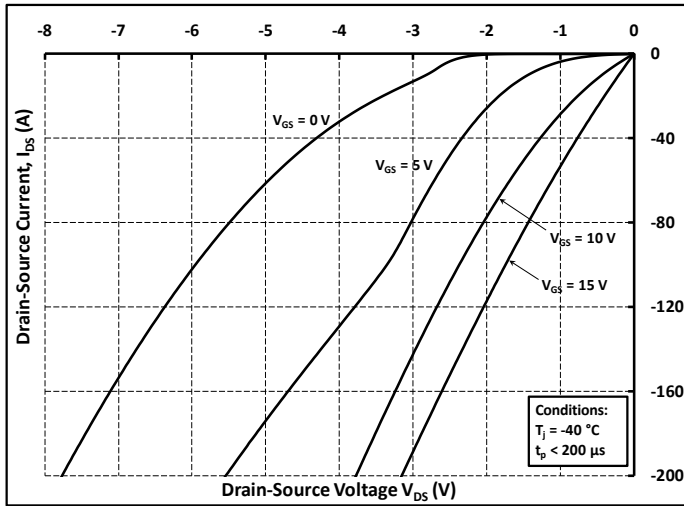


Figure 13. 3rd Quadrant Characteristic at -40 °C

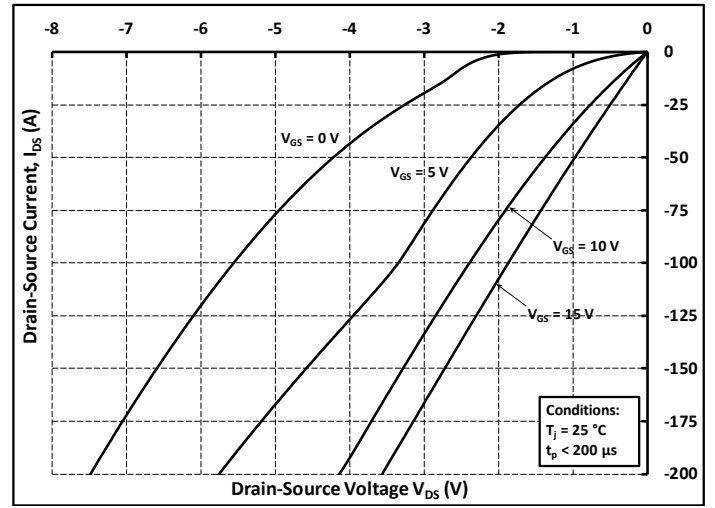


Figure 14. 3rd Quadrant Characteristic at 25 °C

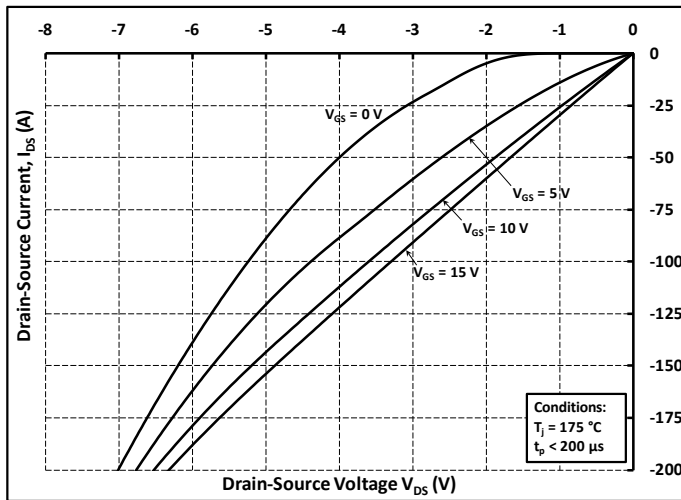


Figure 15. 3rd Quadrant Characteristic at 175 °C

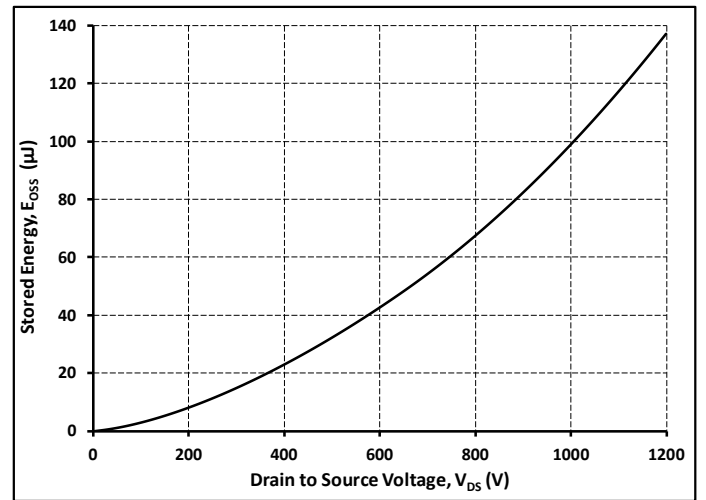


Figure 16. Output Capacitor Stored Energy

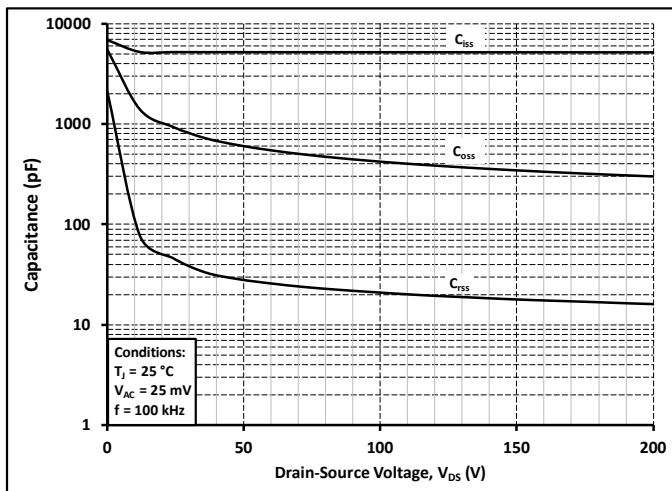


Figure 17. Capacitances vs. Drain-Source Voltage (0 - 200V)

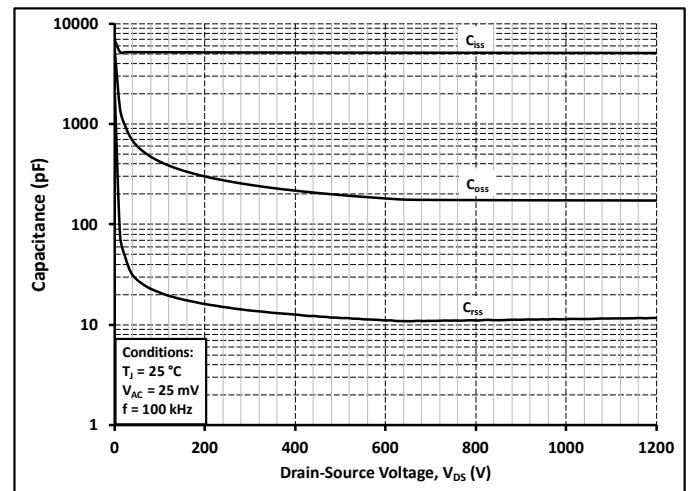


Figure 18. Capacitances vs. Drain-Source Voltage (0 - 1200V)



Typical Performance

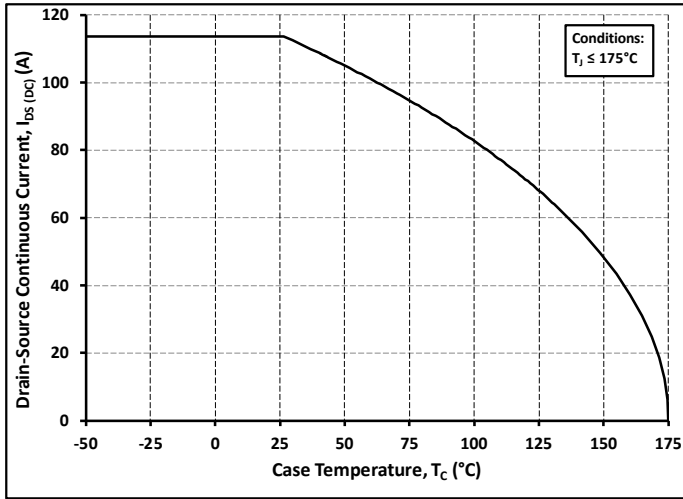


Figure 19. Continuous Drain Current Derating vs. Case Temperature

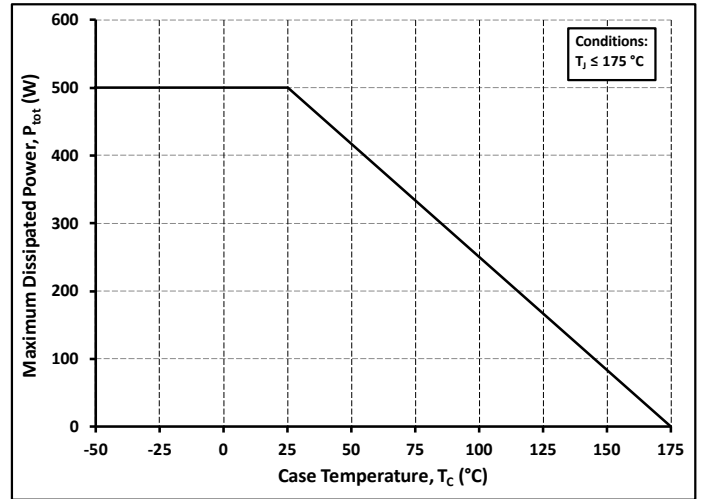


Figure 20. Maximum Power Dissipation Derating vs. Case Temperature

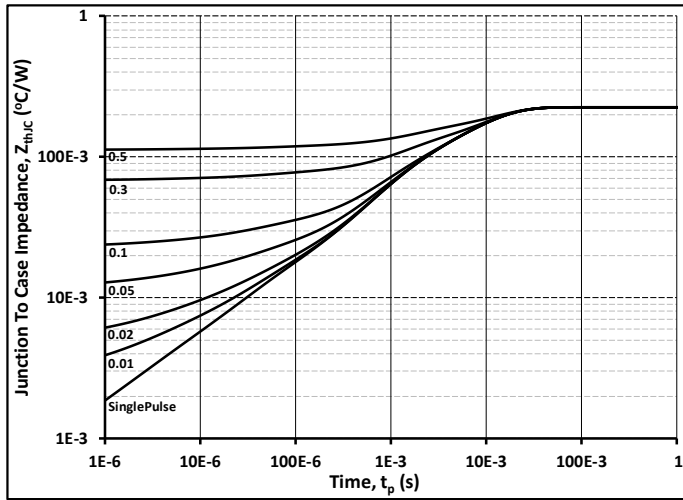


Figure 21. Transient Thermal Impedance (Junction - Case)

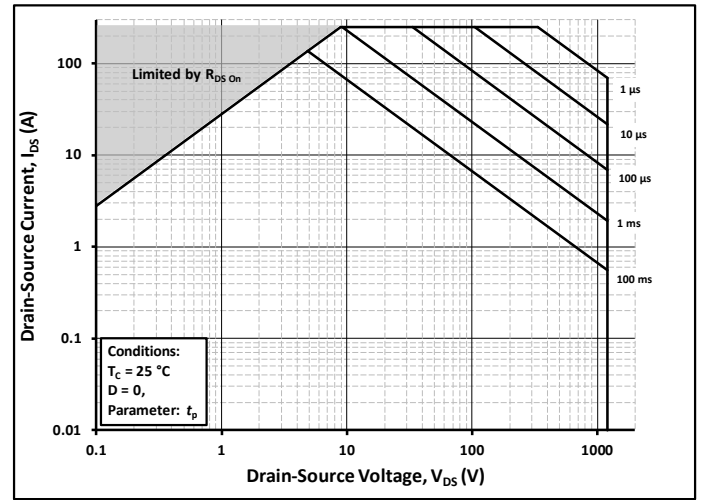


Figure 22. Safe Operating Area

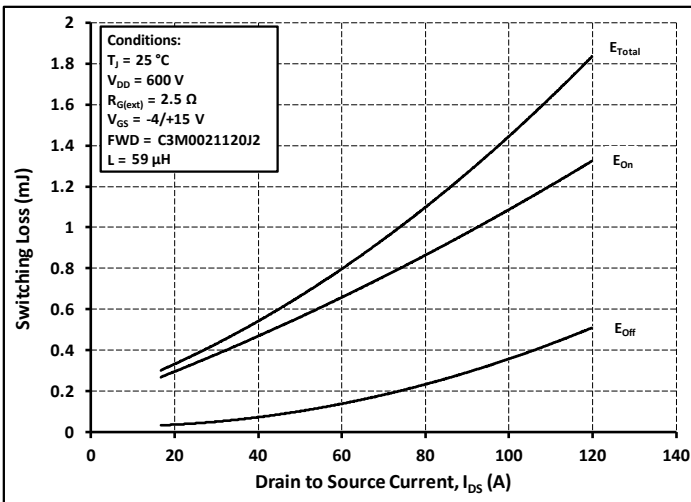


Figure 23. Clamped Inductive Switching Energy vs. Drain Current ($V_{DD} = 600V$)

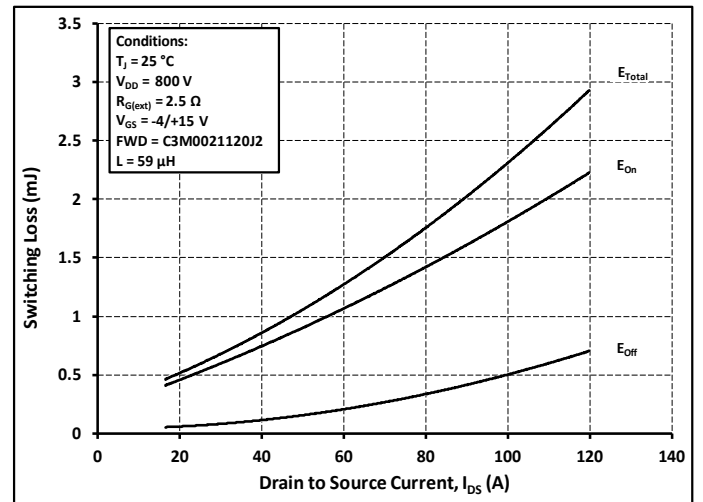


Figure 24. Clamped Inductive Switching Energy vs. Drain Current ($V_{DD} = 800V$)



Typical Performance

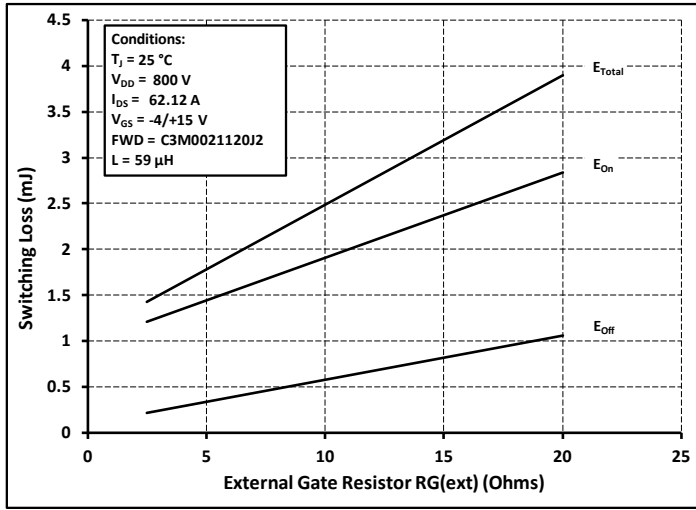


Figure 25. Clamped Inductive Switching Energy vs. $R_{G(ext)}$

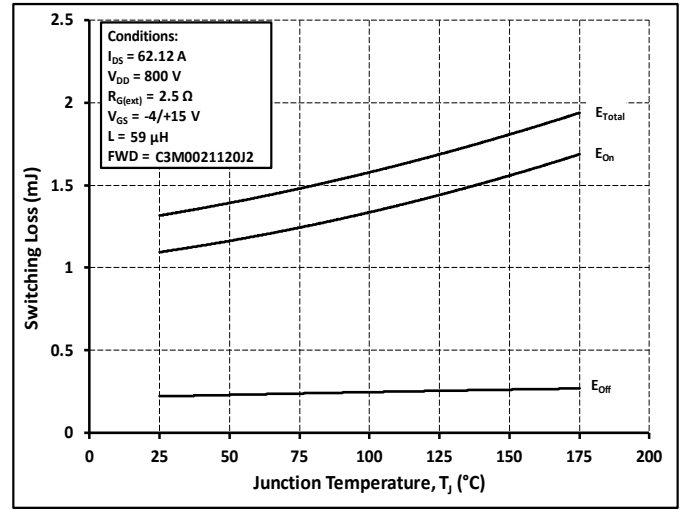


Figure 26. Clamped Inductive Switching Energy vs. Temperature

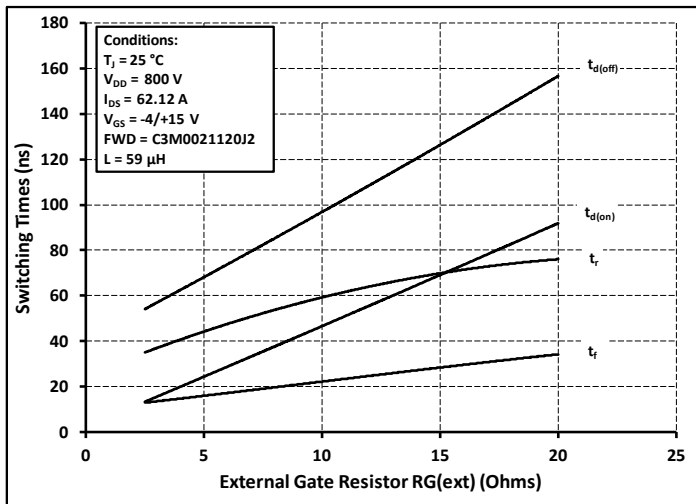


Figure 27. Switching Times vs. $R_{G(ext)}$

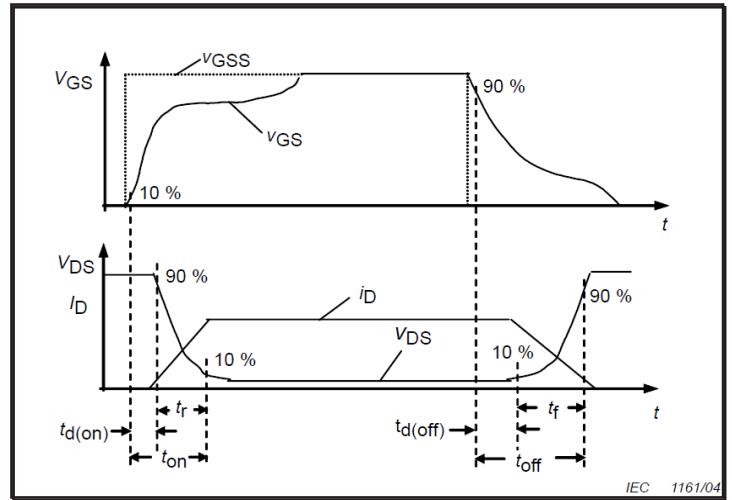


Figure 28. Switching Times Definition



Test Circuit Schematic

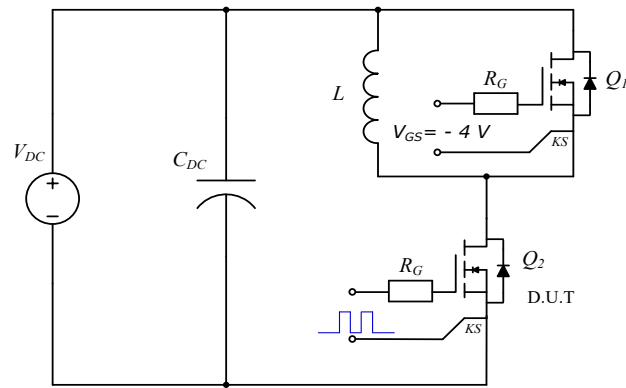
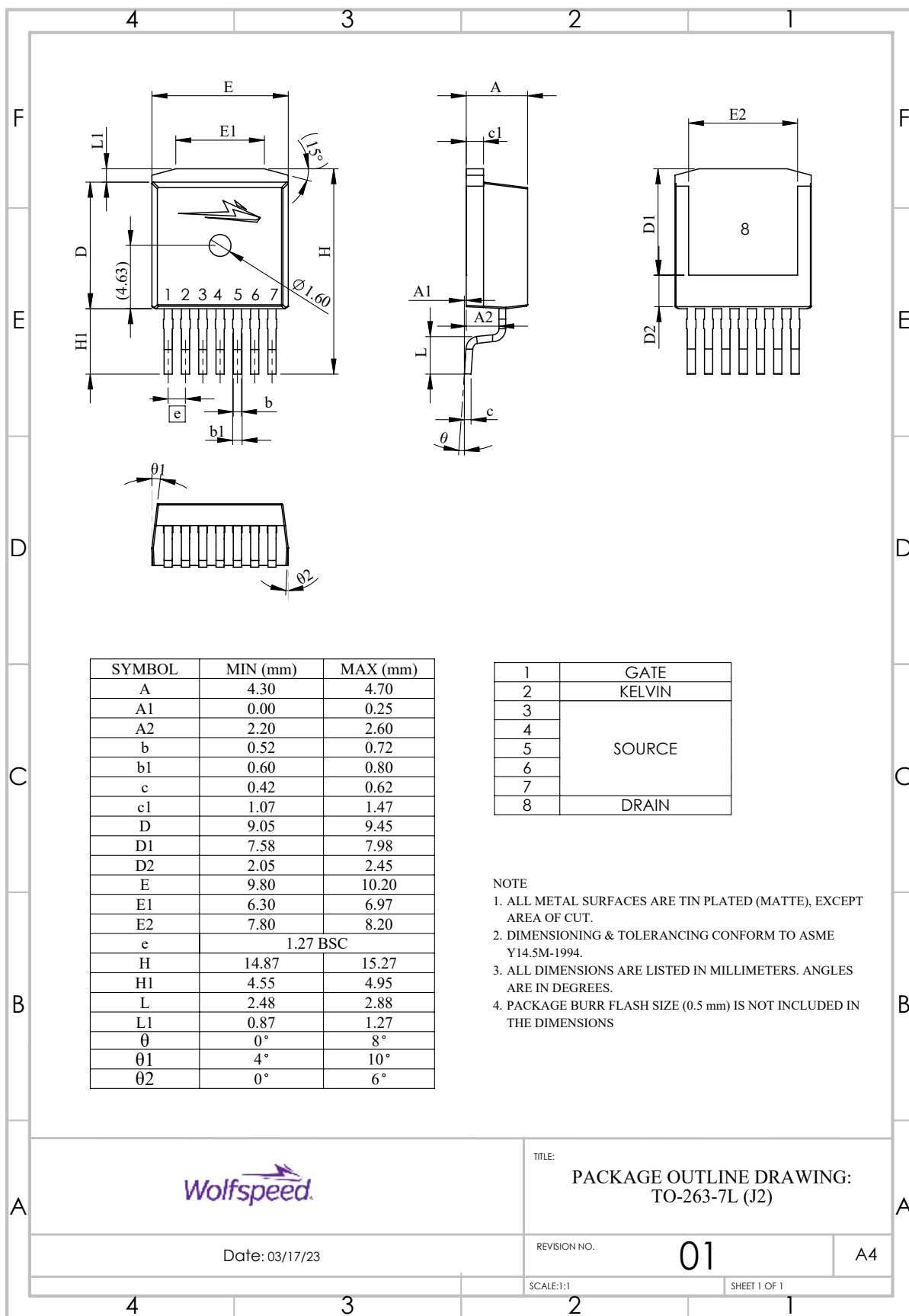


Figure 29. Clamped Inductive Switching Waveform Test Circuit

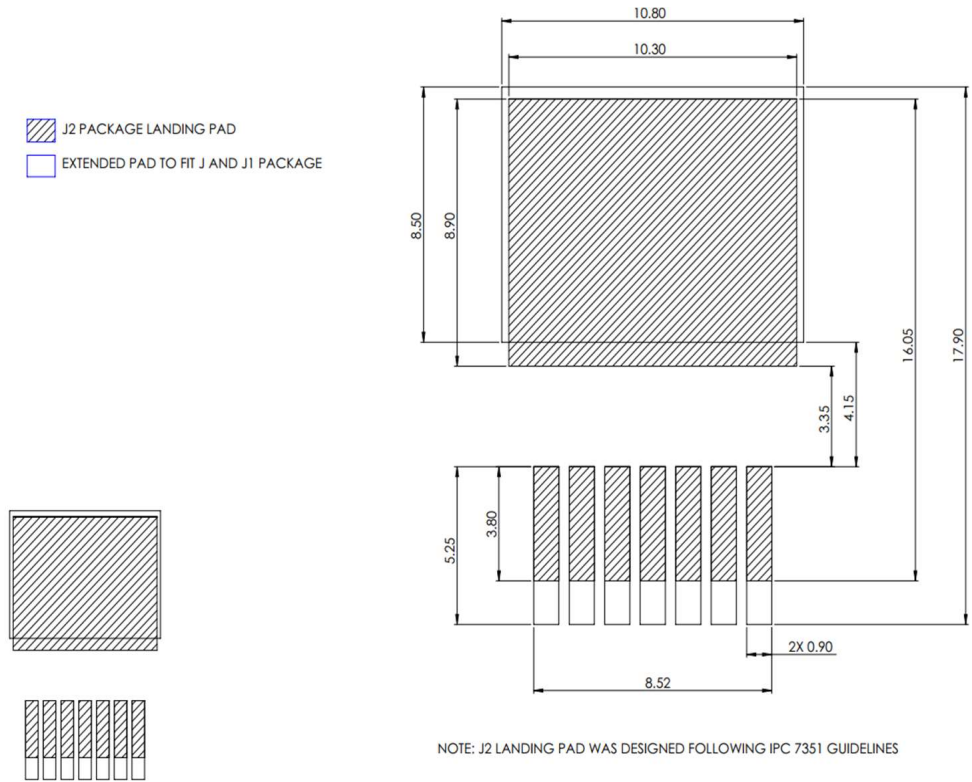
Package Dimensions





Recommended Solder Pad Layout

All dimensions in mm





Revision history

Document Version	Date of release	Description of changes
1	March 2024	Initial release



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